1/5

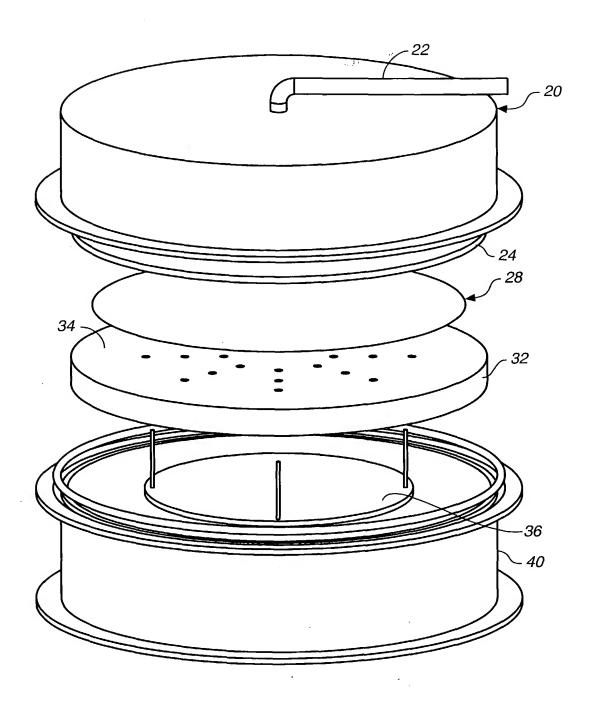


FIG._1
(PRIOR ART)

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Inventors: Wayne Glenn Renken Exp. Mail: EU962645425US
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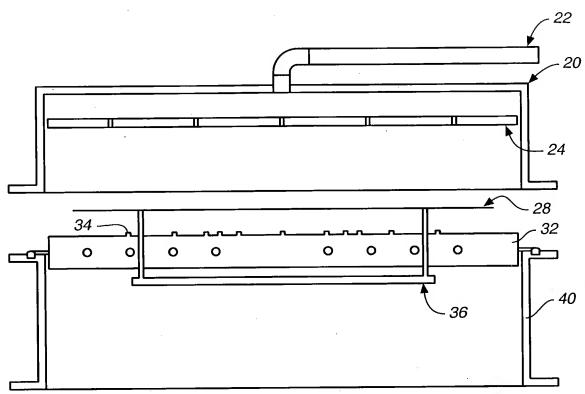


FIG._2 (PRIOR ART)

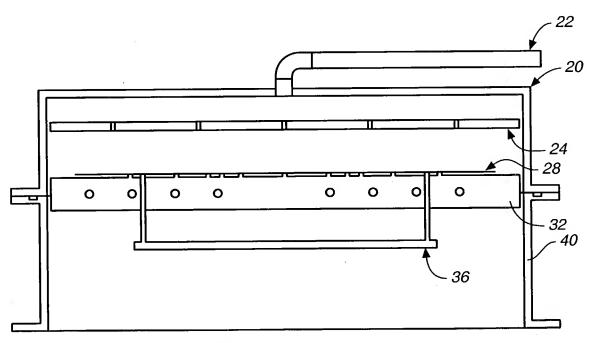
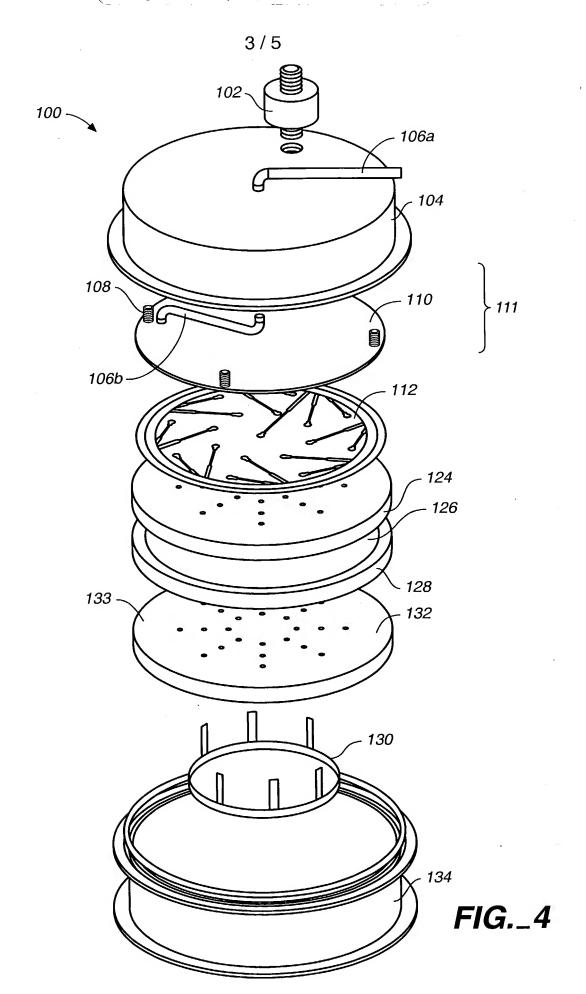
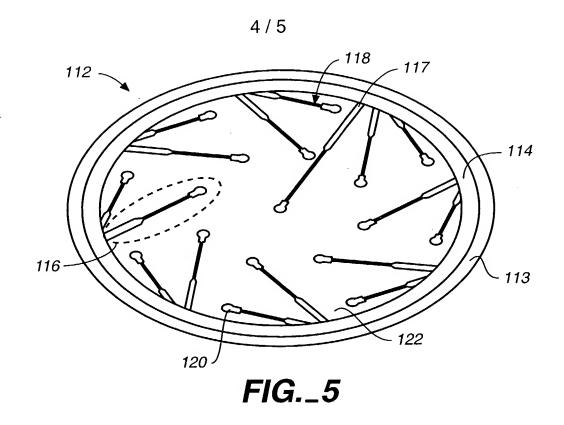


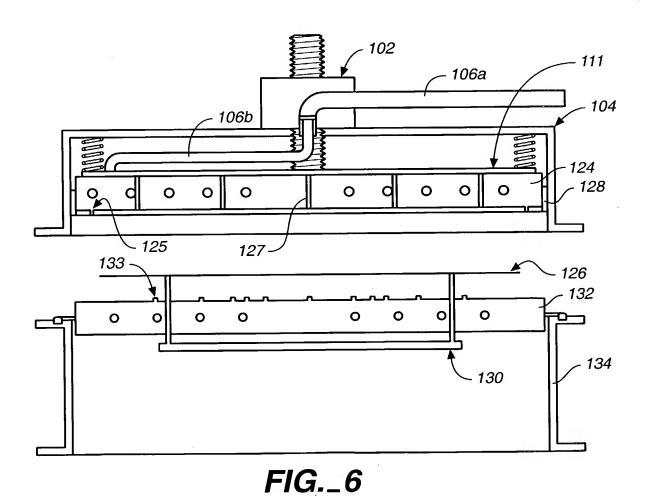
FIG._3 (PRIOR ART)

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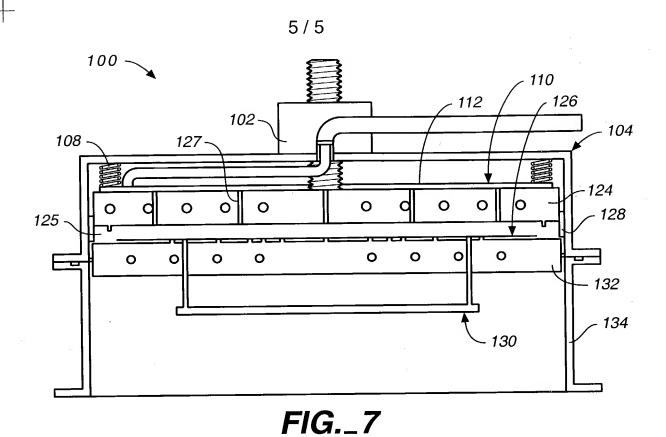
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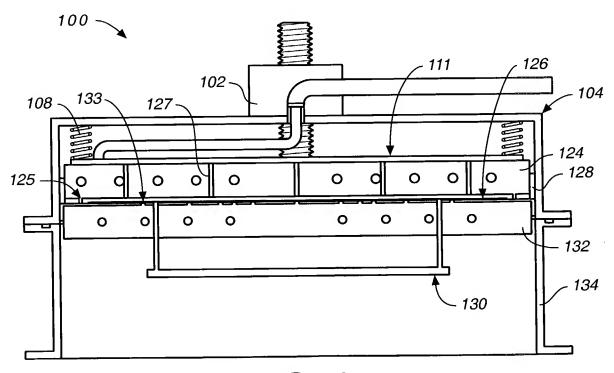


FIG._8